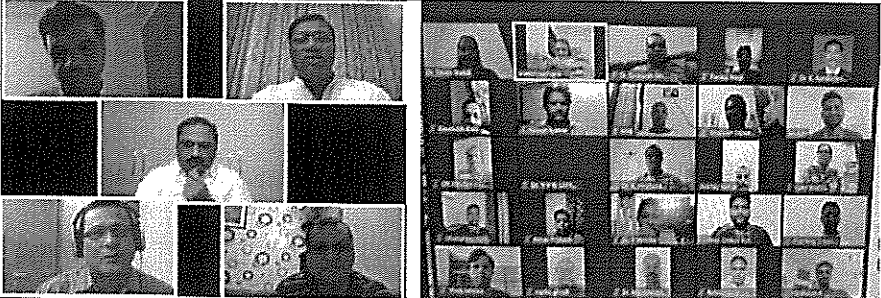





GRIET/6C/G/18-19

EVENT SUMMARY REPORT

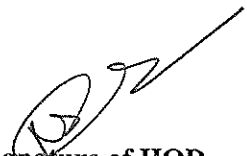
Griet/Other institutes/Organization Address:	Gokaraju Rangaraju Institute of Engineering and Technology, Bachupally, Hyderabad in association with GLA University Mathura				
Department	Mechanical Engineering	Professional Body	Institutional Body		
Nature of the Event (Workshop / Seminar / Guest Lecture / Tech Talk/FDP/GD/ Training Program / Quiz / Presentation/Conference/ Industry Visit/Any Co & Extracurricular Activities)	Conference				
Title / Theme of the Event	10th International Conference on Materials Processing And Characterization				
Details of the Coordinator & Designation	Dr. Swadesh Kumar Singh, Professor, Department of Mechanical Engineering, Hyderabad.				
Event Dates/Days	From	To	No. of Days		
	21/02/2020	23/02/2020	03		
Details of the Speaker / Guest Organization Address:	Details of the speaker has been attached sperearly				
Participants (Teaching Faculty / Non-Teaching Faculty / Students)	No.of Faculty	No. of UG students	No.of PG Students	No.of outside participants	Total Participants
	28	Nil	Nil	549	549
Faculty Names & Designation	List of the participants has been attached separately				

<p>Summary of the Event</p>	<p>An online Faculty Development Programme on Recent Advances in Materials Characterization (RAMC) has been conducted in association with GRIET and NITTTR Chandigarh from 23rd to 28th May, 2020, by using zoom application. This programme has been conducted for six (6) days in which a total of 15 sessions has been conducted. One poll question has been given to the participants at the end every session and the feedback also has been collected for every session.</p>
<p>IRG (in rupees)</p> <p>Deposited A/C no A/C name and date and other details</p> <p>(enclose proof-A/C statement)</p>	<p>Nil</p>
<p>Expenditure (in rupees)</p> <p>(Enclose proof-bills)</p>	<p>Nil</p>
<p>POs attained with this Event</p> <p>(number and description)</p>	<p>Seven (7) POs has been attained with this event</p> <ol style="list-style-type: none"> 1. Ability to analyze problem and interpret the data. 2. Ability to design a system component, or process to meet desired needs in Mechanical Engineering within realistic constraints. 3. Ability to identify, formulate, analyze and interpret data to solve Mechanical Engineering problems. 4. Ability to understand the impact of engineering solutions in a global, economic and societal context. 5. Ability to understand the effect of Mechanical Engineering solutions on environment and to demonstrate the need for sustainable development. 6. Ability to understand professional and ethical responsibility. 7. Ability to demonstrate the management principles in Mechanical Engineering projects.
<p>Photographs of the event</p> <p>(Hard copy and Soft copy)</p>	

Proofs: 1.Certificates copies 2.Profile of Speaker 3.PPT/Material as applicable. etc.,	All the documents are attached separately.
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Signature of Coordinator



Signature of HOD

CHIEF PATRON

Shri Narayan Das Agrawal, Chancellor, GLA University, Mathura, India
Prof. D.S. Chauhan, Vice-Chancellor, GLA University, Mathura, India
Shri G.V.K. RangaRaju, Vice-President, GRES, Hyderabad, India

PATRON

Prof. Anand Mohan Agrawal, Pro-Vice Chancellor, GLA University, Mathura, India
Prof. Anoop Kumar Gupta, Dean Academic Affairs, GLA University, Mathura, India

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Dr. Kuldeep Kumar Saxena, GLA University, Mathura, India
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Prof. Esther Akinlabi, University of Johannesburg, South Africa
Dr. Rajesh Purohit, MANIT, Bhopal, India

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Dr. Kaushik Kumar, BIT Ranchi, India
Dr. R.S. Rana, MANIT, Bhopal, India

JOINT SECRETARY

Dr. Saraswati, RKDF University, Bhopal
Dr. L. Jayahani, GRIET, Hyderabad
Dr. S. K. Dhakad, SATIET, Vidisha

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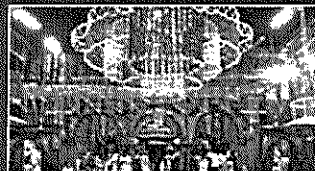
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Dr. Nitin Kotkunde, BITS Pilani, Hyderabad
Dr. K. Suresh, BITS Pilani, Hyderabad
Dr. Inderdeep Singh, IIT Roorkee
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Dr. Vilas Warudkar, MANIT, Bhopal
Dr. Sanjay Shrivastava, MANIT, Bhopal
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Dr. Sulji Kumar Verma, GLA University, Mathura
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Dr. S. Suresh, MANIT, Bhopal
Dr. Bharat Modhra, MANIT, Bhopal
Dr. Raman Nateriya, MANIT, Bhopal
Dr. Nitish Gupta, SGSITS, Indore

ADVISORY COMMITTEE

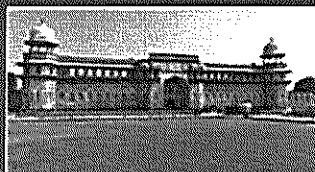
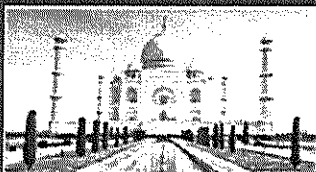
Dr. J.W. Yoon, Deakin University, Australia
Dr. Jaros Law Dretlich, Michigan Technological University, USA
Dr. Bernard Rolfe, Deakin University, Australia
Dr. Fan Gang Tsang, Taiwan
Dr. Stephen Biggar, Victoria University, Melbourne, Australia
Dr. Vekta Krishna, Deputy Director, VSSC, Trivandrum
Dr. Diogo Mariano Neto, University of Coimbra, Portugal
Dr. S.L. Mannan, Former Scientist, ICCAR, Consultant, GIRE
Dr. K. Natsimhan, IIT Bombay
Dr. V. Pancholi, IIT Roorkee
Dr. K. S. Suresh, IIT Roorkee
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Sumit Pantley, Director & Vice-Chancellor
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Dr. I.V. Singh, IIT Roorkee
Dr. T. Raghu, Scientist, DMRL, Hyderabad
Dr. C. Vanitha, NIT Warangal
Dr. C. Padmanabham, Associate Director, ARCI, Hyderabad
Dr. D. Ravi Kumar, IIT Delhi
Dr. Ramesh Kumar, DRDL, Hyderabad
Dr. Ravi Kumar N.V., IIT Madras
Dr. Manoj Kumar Gupta, Scientist, IPR, Gujrat
Dr. A.K. Gupta, BITS Pilani, Hyderabad
Dr. S.K. Panda, IIT Kharagpur
Dr. S.D. Kore, IIT Guwahati
Dr. Balu Naik, JNTU, Hyderabad
Dr. N.D. Mittal, MANIT, Bhopal
Dr. J.L. Bhargoria, MANIT, Bhopal
Dr. Anand Parey, IIT Indore

ABC MATHURA-AGRA

Mathura and Vrindavan are the most important places of pilgrimage for devotees of Lord Krishna. Krishna was born in Mathura and spent his childhood in Vrindavan. The twin city of Mathura, Vrindavan is equally enchanting and captivating, made famous by the world renowned landmarks like ISKCON, Akshaya Patra, Prabhupada mandir and Bankoy/Bharoli Temple. There is Govardhan, the majestic place known for the imposing Govardhan Mountain. A cultural amalgamation center, Mathura has always been strategic in the history on the virtue of being at the crossroad of various trade routes.



Agra, just 55 KM from Mathura, is the home to one of the 7 wonders of the world, the TAJ MAHAL. But that's not the only thing Agra has to boast of. Agra has three UNESCO world Heritage sites, such as Agra Fort and Fatehpur Sikri; and hence makes for a must visit for anyone living in or visiting India.



ACCOMMODATION

Hotels/ Guest Houses in Mathura/Vrindavan provide a range of services that add memorable experience for visitors. Participants are requested to make their own arrangement for travel, boarding and lodging. However, accommodation facility could be arranged on request in advance in nearby hotels/ Guest houses.

TRAVEL

GLA University is situated on the Agra-Delhi National Highway-2 (NH-2). It is well connected with rail/road and by air.

BY AIR: The nearest Airport is Indira Gandhi International Airport, New Delhi. It is 180 KM away to University. From airport, Taxi can be used to reach University and will take hardly 2 and half hours.

BY RAIL/ROAD: Mathura-Agra is situated on the Delhi-Mumbai and Delhi-Chennai route and it well connected to most cities across India. The distance from Mathura Junction to GLA University is 15 km (approx). From the station one can hire the Taxi/Auto very easily for GLA University.

ABOUT ORGANIZING INSTITUTE

GLA University is one of the Premier Universities in India, situated in Northern India. The university was established by our present Chancellor, Shri Narayan Das Agrawal in 1998. The Chancellor envisioned GLA as a quality educational institution to serve the higher education needs of the youth of the region and beyond. The Institute was accorded the status of university under the U.P. State Legislative Act of 2009 (UP Act 21 of 2010). Recently the University was accredited with 'A' grade by UAC. It spread across 310 acres of land and is home to more than 12,000 students, enrolled in a variety of professional courses. It boasts of well designed and maintained buildings, contemporary laboratories, spacious residential complexes and recreational facilities. The facilities of such kind and grandeur make the GLA campus one of the best in the region, providing its students an ideal environment to hone their skills in an increasingly competitive and demanding world.

Under the banner of GLA University, Department of Mechanical Engineering is constantly and consistently working to achieve core objectives of the University. Department facilities state of art laboratories where students can realize their ideas into tangible objects in terms of new technologies and engineering products. Department has Solar Energy Research Centre (SERC), Nano Micro Research Centre (NMRC), Automotive Research Centre and well established workshops and other laboratories.

Department is consistently delivering high quality research. The Faculty of the department are highly qualified and extending their expertise in academic and research.

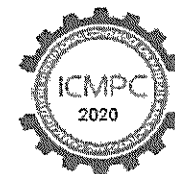
CONTACT US

PAPER SUBMISSION AND TECHNICAL ISSUES

ICMPC Hyderabad, India
Tel: +91-9959870257
Email: icmpc-hyd@griet.ac.in
Website: www.icmpc.com

FOR ACCOMMODATION AND OTHER CONFERENCE ORGANIZATION RELATED ISSUES

Dr. Kuldeep Kumar Saxena, GLA University, Mathura
Phone: 91-7355741069
Email: icmpc_gla@gla.ac.in



in Association with



The Indian Institute of Metals
Mathura Chapter

10TH INTERNATIONAL CONFERENCE ON MATERIALS PROCESSING AND CHARACTERIZATION

NEAR TAJ MAHAL

21st - 23rd February, 2020

ICMPC-2020 CONVENERS

Prof. Piyush Singhal, GLA University, Mathura, India

Dr. Kuldeep Kumar Saxena, GLA University, Mathura, India

Dr. Swadesh Kumar Singh, GRIET, Hyderabad, India

Prof. Esther Akinlabi, University of Johannesburg, South Africa

Dr. Rajesh Purohit, MANIT, Bhopal, India



materialstoday
PROCEEDINGS

ABOUT CONFERENCE

Functional materials, smart materials, intelligent materials – whatever you call them, they will be a key pillar of 21st century technology. Among the modern structural materials there has been a tremendous advancement in science and technology of materials. In recent years, nanostructure materials and nano composites have become increasingly important because of their remarkable properties and permanently growing areas for practical applications. Various aspects of mechanical properties of nano materials including analytical and computational modelling in combination with comprehensive experimental analysis of mechanical behaviour is yet to be investigated. In spite of the rapid progress in this field, mechanical properties of nano materials and composites are still remaining terra incognita in materials science. In the field of massive and complex manufacturing we are now in need of materials, with properties, that can be manipulated according to our needs.

Large spaceplanes like the Space Shuttle would have proven extremely difficult, if not impossible, to build without heat-resistant ceramic tiles to protect them during re-entry. And high-speed forward-swept-wing airplanes like Grumman's experimental X-29 or the Russian Sukhoi S-27 Berkut would not have been possible without the development of composite materials to keep their wings from bending out of shape. Nature is full of magical materials, which are to be discovered in forms suitable to our needs. Such magical materials, also known as intelligent or smart materials, can sense, process, stimulate and actuate a response.

There is an increasing awareness of the benefits to be derived from the development and exploitation of advanced materials and structures in applications ranging from hypersonic to aerospace. With the ability to respond autonomously to changes in their environment, smart systems can offer a simplified approach to the control of various material and system characteristics. Mechanistic understanding from any discipline is the key to the development of materials with capabilities beyond those currently available.

The conference is creating a cross disciplinary summit that transcends departmental, institutional, industrial, public and private research organizations and global barriers and finds itself to be the integration of research and education in the vital field of advanced materials. This conference is mainly aimed in major sectors of advanced processing, material characterization, modelling and simulation, properties, performance and device fabrication.

SCOPE OF CONFERENCE

The role of manufacturing in the country's economy and societal development has long been established through their wealth creation activities. To deepen and broaden our knowledge of materials and to increase innovation and responsiveness to ever-increasing international needs, more in-depth studies of functionally graded materials/layer-made materials are needed at present. The objective of this conference is to bring together experts from academic institutions, industries and research organizations and professional engineers for sharing of knowledge, expertise and experience in the emerging trends related to advanced materials processing, and characterization.

The conference is structured as follows: plenary lectures followed by parallel sessions. Plenary lectures will be delivered by eminent personalities of international repute to introduce the theme of the conference. Each parallel session starts with an invited talk on a specific topic followed by contributed papers.

Thematic topics to be addressed in this conference include, but are not limited to the following:

CONFERENCE TOPICS

Advanced machining processes
Advanced metal forming, bending, welding & casting techniques
Agile/ Intelligence Manufacturing
Agile/ Lean manufacturing
Alternate materials /material substitution
Automation
Clean and Sustainable Manufacturing Processes
Composite and Polymer Manufacturing
Composites, Intermetallics
Design for manufacturing
Design of Experiments
Flexible Manufacturing Systems
Functionally Graded Materials
Future generation materials
Green Manufacturing
Heat Treatment
High-Energy Beam Processing
High-speed Machining
Hybrid Machining
Hydrometallurgy
Innovative Design Methodology
Intelligence Manufacturing
Intelligent Maintenance Systems for Machines and Equipments
Laser Based Manufacturing
Manufacturing with Soft Materials
Material Testing
Meta materials
Metallography
Metrology and Surface Engineering
Micro Machining
Nano materials
Non-destructive Examination
Numerical Control Technology
Numerical Modelling and Simulation
Optimization Techniques in engineering
Powder Metallurgy and Ceramic Forming
Recycling and re-manufacturing of Materials and Components
Reliability Design
Reverse engineering
Robotics
Sensors and Condition monitoring
Separation of the Metal
Smart Machining
SMART materials
Super Alloys
Surface Integrity and Performance of Components by Multiscale Manufacturing
Surface Treatment
Surface, Subsurface, and Interface Phenomena
Thermal Spray
Thermally-Enhanced Processes and Materials
Thin and Thick films
Ultra-Precision Machining
Virtual Manufacturing and Concurrent Engineering
Web-based Manufacturing

CALL FOR PAPERS

Original research papers from faculty, research scholars and scientists from academics, R&D organizations on the above mentioned themes and related topics are invited. The full paper should be sent by e-mail to the provided mail id before 30th Nov 2019. Papers will be selected after rigorous reviews for presentation.

ICMPC-2020 Proceedings will be published by Elsevier journal *Material Today: Proceedings* and will be available on www.sciencedirect.com all these papers will go to Scopus database for future indexing.

IMPORTANT DATES

31st December, 2019	Submission of full papers (In Template)
Authors can register as soon as they get mail from EES or from conference that the article is accepted.	Early bird registration Starts
10th January, 2020	Early bird registration Ends
30th January, 2020	Late Registration Ends

REGISTRATION

It is essential that at least one of the author of the accepted papers and register to participate in the conference, for including the papers in the special issue of the journal. Registration can be done by mailing the complete registration form along with the fee after receiving the acceptance of the paper.

Category	Fee
Faculty/ Research Scholars	Rs 8500/-
Delegates from Industry	Rs 12000/-
Late Registration Fee	Rs 12000/-
Foreign delegates	USD 400

(Bank charges has to be paid by authors only)

* IIM Members will get 20% discount in respective registration fee.

Your registration includes Concurrent/Sessions of technical program, Welcome Breakfast, Morning and Afternoon Refreshment Breaks, and Lunch at the conference venue, Paper Presentation, Attendance to all sessions, Conference bag, Certificate of Presentation, Complimentary city tour.

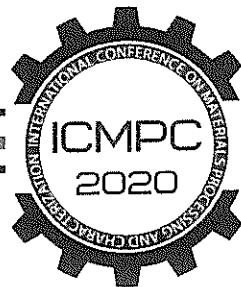
The registration fee shall be paid through crossed demand draft, drawn in favour of Gokaraju Rangaraju Educational Society - ICMPC payable at Hyderabad or by way of electronic money transfer to Axis Bank, Kukatpally, Hyderabad-500075, Account No. 916010080365885 (Bank Code: 003062, IFSC code: UTIB0003062)

For any queries keep in touch with www.icmpc.com

EXHIBITION CUM SPONSORSHIP

An exhibition will be organized concurrently with the conference. The industries who are interested in showcasing their products, equipment may contact the conference chairs. Two delegates sponsored by the exhibitors are allowed to participate in the conference without any extra fee.

Agencies are invited for being co-sponsors of the conference. Delegates will be allowed to attend the conference if any agency supports the conference financially. For future details visit our website.



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MATHURA

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IIM

Metallurgy
Materials Engineering

The Indian Institute of Metals - Mathura Chapter



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CERTIFICATE OF PARTICIPATION

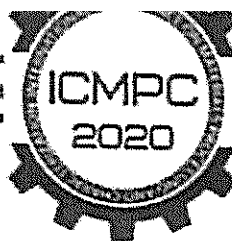
This is to certify that Prof./[✓]Dr./Mr./Ms. TANYA BUDDI
for participating and presenting a paper titled COMPARATIVE STUDY OF ASS 316 L ON FORMABILITY
AT ROOM TEMPERATURE AND SUPER PLASTIC REGION
in *10th International Conference on Materials Processing and Characterization (ICMPC-2020)*
organised by Department of Mechanical Engineering, *GLA University, Mathura*, in association with
Gokaraju Rangaraju Institute of Engineering and Technology (GRIET), Hyderabad and *The Indian
Institute of Metals (IIM)- Mathura Chapter* during *21-23 February 2020*.

Prof. Piyush Singhal
Chairman
IIM- Mathura Chapter

Prof. Swadesh Kr. Singh
Managing Guest Editor
MATPR (Elsevier) & AMPT (T&F)
GR, Hyderabad

Prof. Esther Akinlabi
Convenor, 10th ICMPC
University of Johannesburg
South Africa


Dr. Kuldeep Kr. Saxena
Convenor, 10th ICMPC
GLA University, Mathura





CERTIFICATE OF PARTICIPATION

This is to certify that Prof./Dr./Mr./Ms. RAM. SUBBIAH
for participating and presenting a paper titled A Review on influence of nitriding
on AISI 430 Ferritic Stainless Steel
in *10th International Conference on Materials Processing and Characterization (ICMPC-2020)*
organised by Department of Mechanical Engineering, *GLA University, Mathura*, in association with
Gokaraju Rangaraju Institute of Engineering and Technology (GRIET), Hyderabad and *The Indian*
Institute of Metals (IIM)- Mathura Chapter during *21-23 February 2020*.


Prof. Piyush Singhal
Chairman
IIM- Mathura Chapter


Prof. Swadesh Kr. Singh
Managing Guest Editor
MATPR (Elsevier) & AMPT (T&F)
GRIET, Hyderabad


Prof. Esther Akinlabi
Convenor, 10th ICMPC
University of Johannesburg
South Africa


Dr. Kuldeep Kr. Saxena
Convenor, 10th ICMPC
GLA University, Mathura

ICMPC-2020 21st Feb - 23rd Feb 2020



Welcome
at

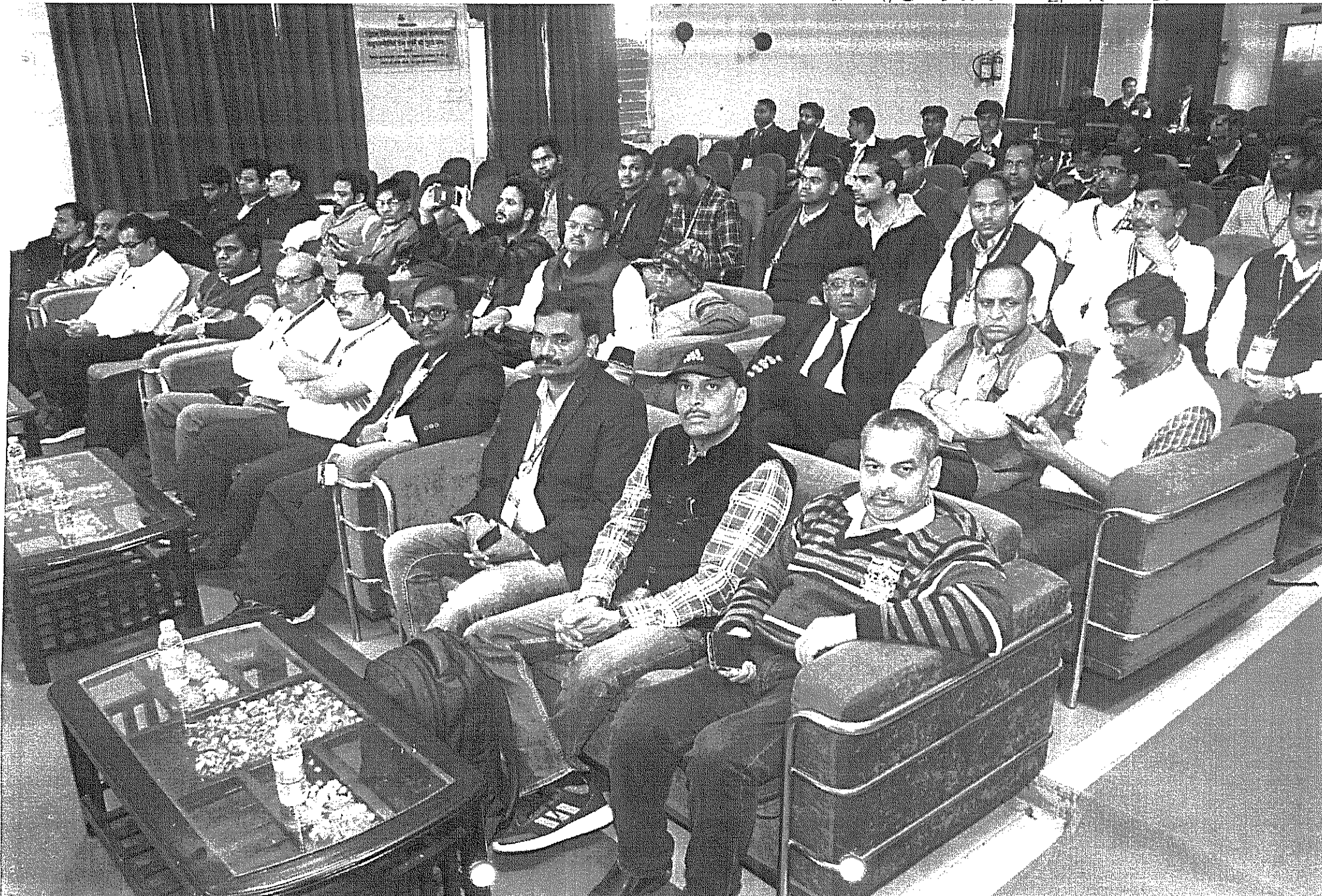
10th International Conference on
Materials Processing and Characterization
ICMPC-2020

21st - 23rd February, 2020



ICMPC - 2020

21st Feb - 23rd Feb 2020





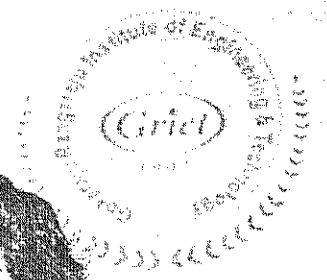
Welcome

at

International Conference on Processes and Characterization

2020

Feb 2020



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